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### ***WiPDA Asia Hosts Distinguished Lineup Of Speakers On WBG Power Technology***

The [Workshop on Wide Bandgap Power Devices and Applications in Asia](#) (WiPDA Asia), which is sponsored by the IEEE Power Electronics Society (PELS), provides a forum for device scientists, circuit designers, and application engineers to share technology updates, research findings, development experience, and application knowledge. WiPDA-Asia 2019 will be held at the Howard International House, Taipei, Taiwan from May 23-25, 2019. This year we have more than 10 keynote speakers, who are leading experts from academia, industry, and research institutes that will share their insights on technology developments and future trends.

Among the speakers from academia, there are six IEEE Fellows including present and past leaders of the IEEE Power Electronics Society. These include Alan Mantooth, past PELS president and a distinguished professor at the Univ. of Arkansas; Hirofumi Akagi, past PELS president and a professor at Tokyo Institute of Technology; Frede Blaabjerg, current PELS president and a professor at Aalborg University; and Yan-Fei Liu, vice president, Technical Operations, PELS and a professor at Queen's University. Other distinguished keynote speakers from academia include Jih-Sheng (Jason) Lai, a professor at Virginia Tech and John Shen, a professor at Illinois Institute of Technology.

The keynote lineup also includes prominent representatives of industry such as Don Tan, also an IEEE Fellow and a past PELS president; Dan Kinzer, CTO of Navitas; Sei-Hyung Ryu, senior research scientist at Wolfspeed; and Hideyuki Okita, a chief engineer at Panasonic.

There will also be three tutorials on high-voltage and/or high-speed power device development, implementation, and application, which will be helpful for those who wish to learn more about wide-bandgap power devices and applications. Also, around 50 technical papers will be presented to share the new findings.

Topics of interest include:

- heteroepitaxial and bulk materials growth
- gate dielectrics and surface passivation
- device structures and fabrication techniques
- device characterization and modeling
- very high efficiency and compact converters
- SOAs including short-circuit, spike; and transient tolerance
- harsh environment (e.g. high temperature) operation and reliability
- packaging, power modules, and ICs
- hard-switched and soft-switched applications
- common-mode and EMI management
- gate drive and other auxiliary circuits
- high-performance passive components
- applications in renewable energy and storage, transportation, industrial drives, and grid power.

Registration for WiPDA-Asia 2019 is now open. We sincerely invite you to come and join us at this wonderful event, to learn, share and exchange ideas on the latest research for wide bandgap power devices and applications. For more information see the workshop [website](#).